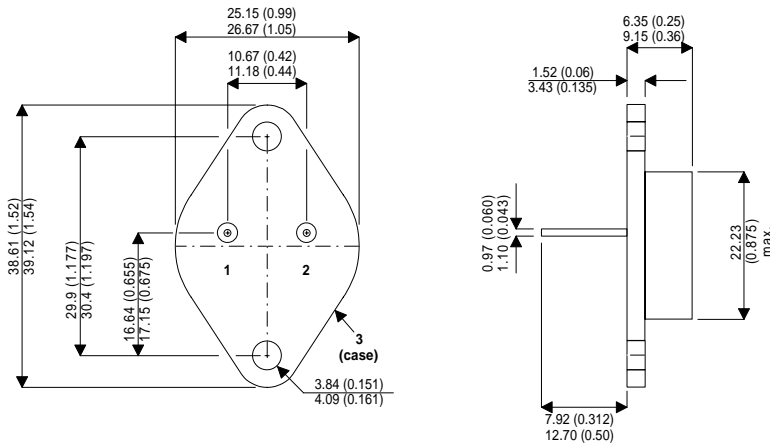


TO-3 (TO-204AA) Package Outline.  
Dimensions in mm (inches)

## 4TH GENERATION MOSFET

### N-CHANNEL ENHANCEMENT MODE HIGH VOLTAGE POWER MOSFETS



Pin 1 – Gate

Pin 2 – Source

Case – Drain

$V_{DSS}$       **500V**  
 $I_{D(cont)}$     **14.5A**  
 $R_{DS(on)}$      **0.40 $\Omega$**

### ABSOLUTE MAXIMUM RATINGS ( $T_{case} = 25^{\circ}C$ unless otherwise stated)

$V_{DSS}$	Drain – Source Voltage	500	V
$I_D$	Continuous Drain Current	14.5	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	58	A
$V_{GS}$	Gate – Source Voltage	$\pm 30$	V
$P_D$	Total Power Dissipation @ $T_{case} = 25^{\circ}C$	198	W
	Derate Linearly	1.584	W/ $^{\circ}C$
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	$^{\circ}C$
$T_L$	Lead Temperature : 0.063" from Case for 10 Sec.	300	

### STATIC ELECTRICAL RATINGS ( $T_{case} = 25^{\circ}C$ unless otherwise stated)

	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain – Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	500			V
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{GS} = 0V$ )	$V_{DS} = V_{DSS}$			250	$\mu A$
		$V_{DS} = 0.8V_{DSS}, T_C = 125^{\circ}C$			1000	
$I_{GSS}$	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 100$	nA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 1.0mA$	2		4	V
$I_{D(ON)}$	On State Drain Current <sup>2</sup>	$V_{DS} > I_{D(ON)} \times R_{DS(ON)}$ Max $V_{GS} = 10V$	14.5			A
$R_{DS(ON)}$	Drain – Source On State Resistance <sup>2</sup>	$V_{GS} = 10V, I_D = 0.5 I_D [Cont.]$			0.40	$\Omega$

1) Repetitive Rating: Pulse Width limited by maximum junction temperature.

2) Pulse Test: Pulse Width < 380 $\mu S$ , Duty Cycle < 2%

**DYNAMIC CHARACTERISTICS**

	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$		1430	1800	pF
$C_{oss}$	Output Capacitance	$V_{DS} = 25V$		330	465	
$C_{rss}$	Reverse Transfer Capacitance	$f = 1MHz$		130	200	
$Q_g$	Total Gate Charge <sup>3</sup>	$V_{GS} = 10V$		64	105	nC
$Q_{gs}$	Gate – Source Charge	$V_{DD} = 0.5 V_{DSS}$		8.7	12	
$Q_{gd}$	Gate – Drain (“Miller”) Charge	$I_D = I_D [Cont.] @ 25^\circ C$		34	51	
$t_{d(on)}$	Turn-on Delay Time	$V_{GS} = 15V$		12	24	ns
$t_r$	Rise Time	$V_{DD} = 0.5 V_{DSS}$		21	42	
$t_{d(off)}$	Turn-off Delay Time	$I_D = I_D [Cont.] @ 25^\circ C$		51	77	
$t_f$	Fall Time	$R_G = 1.8\Omega$		27	54	

**SOURCE – DRAIN DIODE RATINGS AND CHARACTERISTICS**

	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	(Body Diode)			14.5	A
$I_{SM}$	Pulsed Source Current <sup>1</sup>	(Body Diode)			58	
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS} = 0V, I_S = -I_D [Cont.]$			1.3	V
$t_{rr}$	Reverse Recovery Time	$I_S = -I_D [Cont.], di_S / dt = 100A/\mu s$	148	296	592	ns
$Q_{rr}$	Reverse Recovery Charge	$I_S = -I_D [Cont.], di_S / dt = 100A/\mu s$	2.2	4.4	8.8	$\mu C$

**SAFE OPERATING AREA CHARACTERISTICS**

	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
SOA1	Safe Operating Area	$V_{DS} = 0.4V_{DSS}, t = 1 \text{ Sec.}$ $I_{DS} = P_D / 0.4V_{DSS}$	198			W
SOA2	Safe Operating Area	$V_{DS} = P_D / I_D [Cont.]$ $I_{DS} = I_D [Cont.], t = 1 \text{ Sec.}$	198			W
$I_{LM}$	Inductive Current Clamped		58			A

**THERMAL CHARACTERISTICS**

	Characteristic	Min.	Typ.	Max.	Unit
$R_{\theta JC}$	Junction to Case			0.63	$^\circ C/W$
$R_{\theta JA}$	Junction to Ambient			30	

1) Repetitive Rating: Pulse Width limited by maximum junction temperature.

2) Pulse Test: Pulse Width < 380 $\mu s$ , Duty Cycle < 2%

3) See MIL–STD–750 Method 3471



CAUTION — Electrostatic Sensitive Devices. Anti-Static Procedures Must Be Followed.